PRODUCT / PROCESS CHANGE NOTIFICATION

| 1. PCN basic data | | |
|----------------------|--|--|
| 1.1 Company | | STMicroelectronics International N.V |
| 1.2 PCN No. | | ADG/19/11606 |
| 1.3 Title of PCN | | Additional Assembly and Test Location in China for the EMIF06-MSD02N16 |
| 1.4 Product Category | | EMIF06-MSD02N16 |
| 1.5 Issue date | | 2019-08-01 |

| 2. PCN Team | |
|---------------------------|--------------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | ROBERTSON HEATHER |
| 2.1.2 Phone | +1 8475853058 |
| 2.1.3 Email | heather.robertson@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Richard RENARD |
| 2.1.2 Marketing Manager | Eric PARIS |
| 2.1.3 Quality Manager | Jean-Paul REBRASSE |

| 3. Change | | |
|--------------|--------------------|----------------------------|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
| Machines | (Not Defined) | Subco in China (Carsem) |

| 4. Description of change | | |
|---|-----------------------------|---|
| | Old | New |
| 4.1 Description | Thailand (subco 1) (Carsem) | Thailand (subco 1) (Utac) CHINA (subco 2) (Carsem) |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | no | |

| 5. Reason / motivation for change | | |
|-----------------------------------|---|--|
| 5.1 Motivation | increase of the manufacturing capacity for a better service | |
| 5.2 Customer Benefit | CAPACITY INCREASE | |

| 6. Marking of parts / traceability of change | |
|--|--|
| 6.1 Description | internal codification, marking and QA number |

| 7. Timing / schedule | | |
|-------------------------------------|--------------|--|
| 7.1 Date of qualification results | 2019-05-24 | |
| 7.2 Intended start of delivery | 2019-09-02 | |
| 7.3 Qualification sample available? | Upon Request | |

| 8. Qualification / Validation | | | |
|---|-------------|---------------|--|
| 8.1 Description | | | |
| 8.2 Qualification report and qualification results | In progress | Issue Date | |

9. Attachments (additional documentations)

11606 Public product.pdf 11606 PCN qualif EMIF06-MSD02N16 subco_China.pdf

| 10. Affected parts | | |
|-------------------------|--|--------------------------|
| 10. 1 Current | | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 0.1.1 Customer Part No 10.1.2 Supplier Part No 10.1.2 Supplier Part No | |
| | EMIF06-MSD02N16 | |



Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : Additional Assembly and Test Location in China for the EMIF06-MSD02N16 *PCN Reference :* ADG/19/11606

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

| EMIF06-MSD02N16 | | |
|-----------------|--|--|
|-----------------|--|--|

IMPORTANT NOTICE - PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics - All rights reserved